CLAIMS

What is claimed is:

1. A process for dressing a saw blade, comprising:

rotating the saw blade on a spindle; and

ablating an edge portion of the saw blade using a laser thereby dressing said saw blade.

2. The process according to claim 1, wherein ablating said edge portion of the saw blade comprises ablating the edge portion of the saw blade using a high energy laser.

3. The process according to claim 1, further comprising marking the saw blade to indicate that said saw blade is dressed and to indicate the number of times the saw blade has been dressed.

4. A process for reworking a saw blade used in wafer dicing and singulation of molded array IC packages, the process comprising:

mounting the saw blade on a spindle in a dressing device;

rotating the saw blade on said spindle;

feeding said saw blade into a laser beam for removing an edge portion of the saw blade.

5. The process according to claim 4, wherein feeding comprises feeding the saw blade into a high energy laser beam.

6. The process according to claim 4, further comprising marking the saw blade with an indicator to thereby indicate that the saw blade is reworked.

7. A process for dressing a saw blade used in wafer dicing and singulation of molded array IC packages, the process comprising:

rotating the saw blade on a spindle; and

ablating an edge portion of the saw blade using a high energy laser thereby dressing said saw blade.